

Service
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HMP7000B/93



Service Manual

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Version 1.2



PHILIPS

HMP7000/93 SPECIFICATION:

Note

- Specification and design are subject to change without notice.

File

- Video: MPEG 1/2/4(MPEG 4 Part 2), H.264,VC-1, H.263,VP6(640 × 480), DivX Plus HD, DivX 3/4/5/6, Xvid, RMVB 8/9, RM, WMV (V9), AVI, TS, M2TS, TP,TRP, ISO,VOB, DAT, MP4, MPG, MOV (MPEG 4, H.264), ASF, FLV(640 × 480), MKV, M4V.
- Audio: Dolby digital, AAC, RA, OGG, MKA, MP3, WAV, APE, FLAC, DTS, LPCM, PCM, WMA (V9), IMP/MS ADPCM, WMA Pro
- Picture: .JPEG, .JPG, .PNG, .TIFF, .GIF (unanimated GIF), .BMP, .TIF, .M-JPEG, .HD-JPEG

USB storage device

- Compatibility: Hi-Speed USB (2.0)

Subtitle support

- .srt, .sub, .smi, .ssa, .ass, .txt, .psb, .idx+.sub

SD card

- Compatibility: SDHC 2.0 (up to 32 GB)

Video

- Signal system: PAL /NTSC
- Composite video output: 1 Vpp ~ 75 ohm
- HDMI output: 480i, 480p, 576i, 576p, 720p, 1080i, 1080p, 1080p24

Audio

- Analog stereo output
- Signal to noise ratio (1 kHz): > 90 dB (A-weighted)
- Dynamic Range (1 kHz): > 80 dB (A-weighted)
- Frequency response: +/-0.2 dB
- Digital output: Optical

Main Unit

- Dimensions (L × W × H): 160 × 91 × 54.1 mm
- Net Weight: 0.34 Kg
- Input: 100-240V~ 50/60Hz, 15W

Power

- Power consumption: < 15 W
- Power consumption in standby mode: < 1 W

REMOTE CONTROL

Use your remote control to control the play.

Function	Buttons / Actions
Stop the play.	■
Pause or resume the play.	▶
Skip to the previous/ next media file.	◀ / ▶
Return to the home page.	🏠
Zoom in or out.	Press  repeatedly. <ul style="list-style-type: none"> To pan through an enlarged photo, press ▲ ▼◀▶.
Search backward/forward fast.	Press ◀◀ / ▶▶ repeatedly to select a speed.
Access subtitle settings.	字幕
Rotate a photo.	Press ▲ / ▼.
Navigate menus.	▲ ▼ ◀ ▶
Confirm a selection or entry.	OK
Access option menus during play or in the file list.	☰
Access the file editing menu in the file folder list.	EDIT
Display current playback information.	📄
Return to the previous menu.	↶

Safety instruction, Warning & Notes

Safety instruction

1. General safety

Safety regulations require that during a repair:

- . Connect the unit to the mains via an isolation transformer.
- . Replace safety components indicated by the symbol ▲, only by components identical to the original ones. Any other component substitution (other than original type) may increase risk of fire or electrical shock hazard.

Safety regulations require that after a repair, you must return the unit in its original condition. Pay, in particular, attention to the following points:

- . Route the wires/cables correctly, and fix them with the mounted cable clamps.
- . Check the insulation of the mains lead for external damage.
- . Check the electrical DC resistance between the mains plug and the secondary side:
 - 1) Unplug the mains cord, and connect a wire between the two pins of the mains plug.
 - 2) Set the mains switch the "on" position (keep the mains cord unplug).
 - 3) Measure the resistance value between the mains plug and the front panel, controls, and chassis bottom.
 - 4) Repair or correct unit when the resistance measurement is less than 1M Ω .
 - 5) Verify this, before you return the unit to the customer/user (ref. UL-standard no. 1492).
 - 6) Switch the unit "off", and remove the wire between the two pins of the mains plug.

2.Laser safety

This unit employs a laser. Only qualified service personnel may remove the cover, or attempt to service this device (due to possible eye injury).

Laser device unit

Type	: Semiconductor laser GaAlAs
Wavelength	: 650nm (DVD)
	: 780nm (VCD/CD)
Output power	: 7mW (DVD)
	: 10mW (DVD /CD)

Beam divergence: 60 degree

Note: Use of controls or adjustments or performance of procedure other than those specified herein, may result in hazardous radiation exposure. Avoid direct exposure to beam.

Warning

1. General

. All ICs and many other semiconductors are susceptible to electrostatic discharges (ESD). Careless handling during repair can reduce life drastically. Make sure that, during repair, you are at the same potential as the mass of the set by a wristband with resistance. Keep components and tools at this same potential. Available ESD protection equipment:

- 1) Complete kit ESD3 (small tablemat, wristband, connection box, extension cable and earth cable) 4822 310 10671.
- 2) Wristband tester 4822 344 13999.

. Be careful during measurements in the live voltage section. The primary side of the power supply, including the heat sink, carries live mains voltage when you connect the player to the mains (even when the player is "off!"). It is possible to touch copper tracks and/or components in this unshielded primary area, when you service the player. Service personnel must take precautions to prevent touching this area or components in this area. A "lighting stroke" and a stripe-marked printing on the printed wiring board, indicate the primary side of the power supply.

. Never replace modules, or components, while the unit is "on".

2. Laser

- . The use of optical instruments with this product, will increase eye hazard.
- . Only qualified service personnel may remove the cover or attempt to service this device, due to possible eye injury.
- . Repair handling should take place as much as possible with a disc loaded inside the player.
- . Text below is placed inside the unit, on the laser cover shield:

CAUTION: VISIBLE AND INVISIBLE LASER RADIATION WHEN OPEN, AVOID EXPOSURE TO BEAM.

Notes: Manufactured under licence from Dolby Laboratories. The double-D symbol is trademarks of Dolby Laboratories, inc. All rights reserved.

Notes

Lead-Free requirement for service

IDENTIFICATION:

Regardless of special logo (not always indicated) 

One must treat all sets from 1.1.2005 onwards, according next rules.

Important note: In fact also products a little older can also be treated in this way as long as you avoid mixing solder-alloys (leaded/ lead-free). So best to always use SAC305 and the higher temperatures belong to this.

Due to lead-free technology some rules have to be respected by the workshop during a repair:

- Use only lead-free solder alloy Philips SAC305 with order code 0622 149 00106. If lead-free solder-paste is required, please contact the manufacturer of your solder-equipment. In general use of solder-paste within workshops should be avoided because paste is not easy to store and to handle.
- Use only adequate solder tools applicable for lead-free solder alloy. The solder tool must be able
 - To reach at least a solder-temperature of 400°C,
 - To stabilize the adjusted temperature at the solder-tip
 - To exchange solder-tips for different applications.
- Adjust your solder tool so that a temperature around 360°C – 380°C is reached and stabilized at the solder joint. Heating-time of the solder-joint should not exceed ~ 4 sec. Avoid temperatures above 400°C otherwise wear-out of tips will rise drastically and flux-fluid will be destroyed. To avoid wear-out of tips switch off un-used equipment, or reduce heat.
- Mix of lead-free solder alloy / parts with leaded solder alloy / parts is possible but PHILIPS recommends strongly to avoid mixed solder alloy types (leaded and lead-free). If one cannot avoid, clean carefully the solder-joint from old solder alloy and re-solder with new solder alloy (SAC305).

- Use only original spare-parts listed in the Service-Manuals. Not listed standard-material (commodities) has to be purchased at external companies.
- Special information for BGA-ICs:
 - always use the 12nc-recognizable soldering temperature profile of the specific BGA (for de-soldering always use highest lead-free temperature profile, in case of doubt)
 - lead free BGA-ICs will be delivered in so-called 'dry-packaging' (sealed pack including a silica gel pack) to protect the IC against moisture. After opening, dependent of MSL-level seen on indicator-label in the bag, the BGA-IC possibly still has to be baked dry. This will be communicated via AYS-website.
- Do not re-use BGAs at all.
- For sets produced before 1.1.2005, containing leaded soldering-tin and components, all needed spare-parts will be available till the end of the service-period. For repair of such sets nothing changes.
- On our website:

www.atyourservice.ce.Philips.com

You find more information to:

BGA-de-/soldering (+ baking instructions)
 Heating-profiles of BGAs and other ICs used in Philips-sets

You will find this and more technical information within the "magazine", chapter "workshop news".
 For additional questions please contact your local repair-helpdesk.

LOCATION OF PCB BOARDS

Main Board:

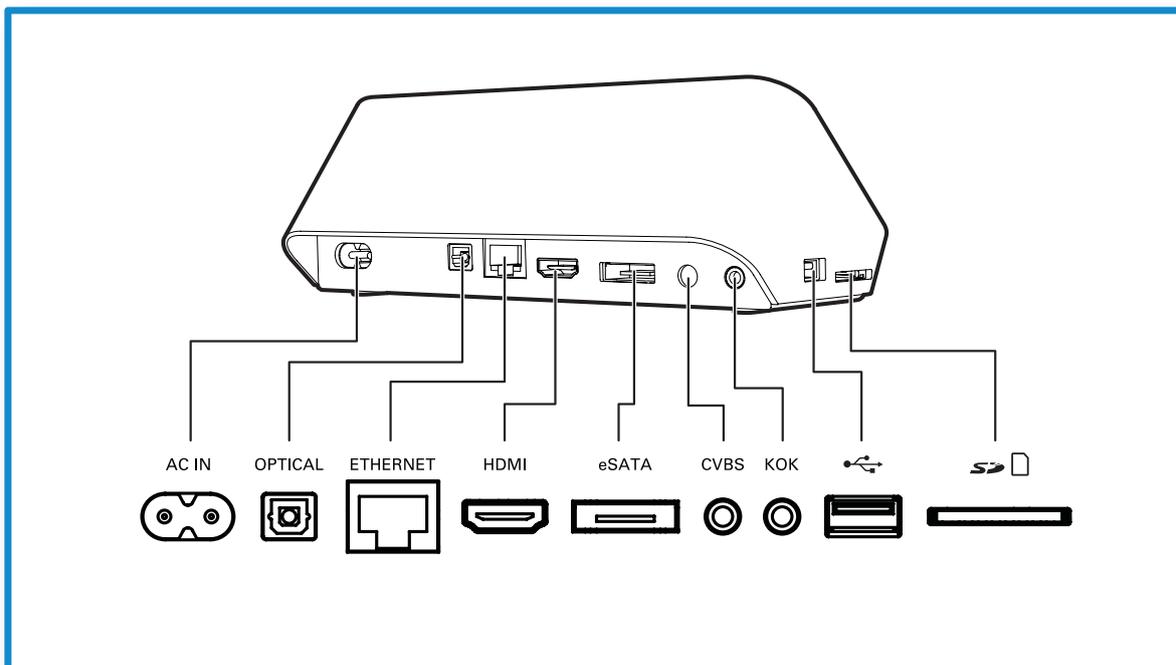
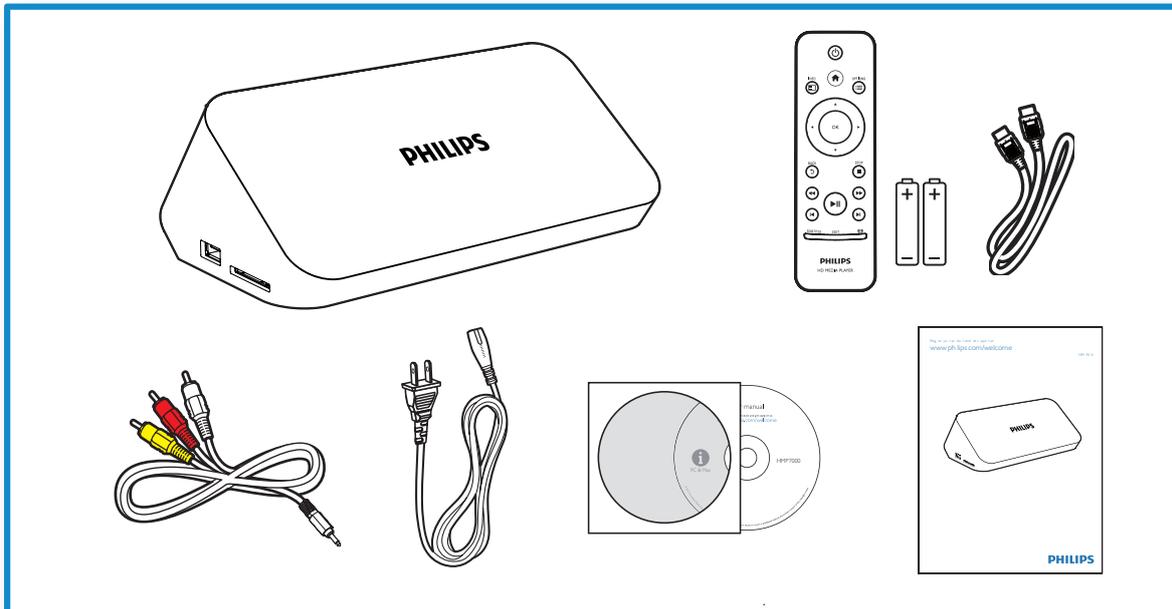


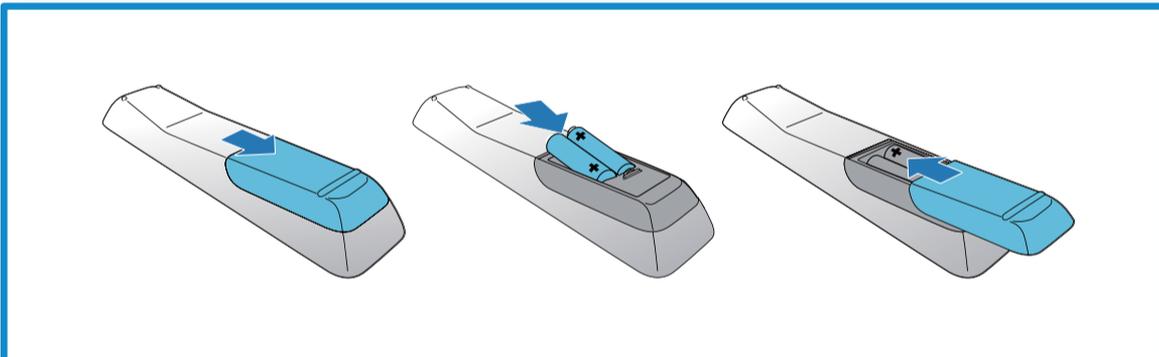
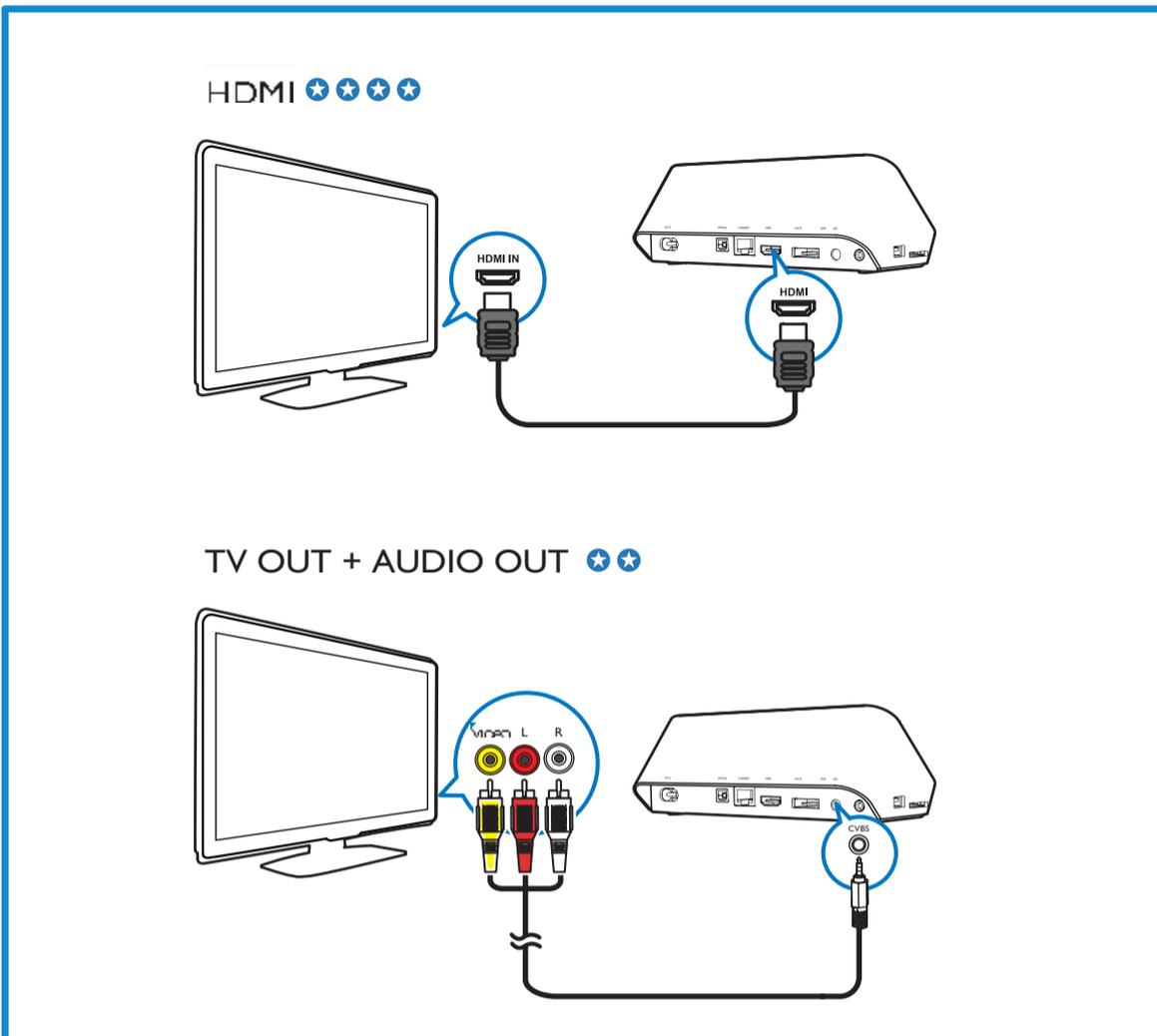
Repair Scenario Matrix

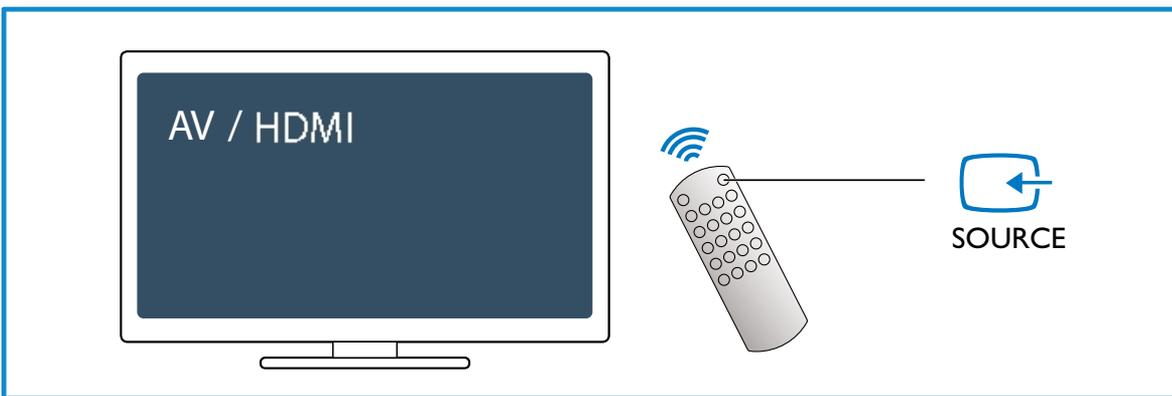
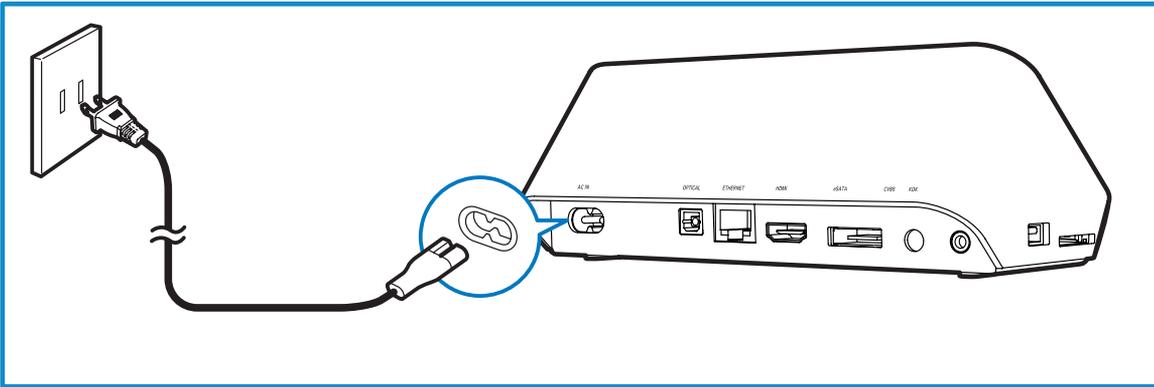
Type/Versions Board in used	HMP7000		HMP7000B
	/93	/12	/93
Main Board	C/M	M	C/M
Power Board	M	M	M

*M: Module Level Replacement

*C: Component Level Repair







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